

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (Currently amended) A flip chip package comprising:
a chip, the chip comprising a top surface, a bottom surface and one or more side surfaces disposed between the top and bottom surfaces;
a substrate, the substrate comprising an upper surface;
a plurality of reflowed solder bumps, the reflowed solder bumps electrically coupling the top surface with an adjacent portion of the upper surface; and
a monolithic element comprising solidified resin, the monolithic element resulting from a single molding process, the monolithic element encapsulating and adhesively bonded to (i) substantially all of the one or more side surfaces, (ii) a substantial portion of the upper surface, and (iii) the plurality of reflowed solder bumps located in a gap between the top surface and the upper surface.
2. (Original) The flip chip package of claim 1, wherein the solidified resin does not encapsulate the bottom surface.
3. (Original) The flip chip package of claim 2, wherein the resin further comprises a filler material.
4. (Original) The flip chip package of claim 3, wherein the filler material comprises silica microspheres.

5. (Original) The flip chip package of claim 1, wherein the resin encapsulates substantially all of the one or more side surfaces.
6. (Original) The flip chip package of claim 5, wherein the resin does not encapsulate the bottom surface.
7. (Original) The flip chip package of the claim 1, wherein the solidified resin comprises an epoxy.
8. (Original) The flip chip package of claim 1, wherein the substrate is a thin substrate.
9. (Original) The flip chip package of claim 1, wherein the substrate is comprised of a polymeric material.
10. (Original) The flip chip package of claim 8, wherein the substrate is approximately 0.05mm to 0.5mm thick.
11. (Original) The flip chip package of claim 1, further comprising at least one passive component electrically coupled with the substrate.
12. (Original) The flip chip package of claim 11, wherein the solidified resin fills a gap between a first surface of the at least one passive component and an adjacent surface of the substrate.
13. (Original) The flip chip package of claim 11, wherein the solidified resin fully encapsulates the at least one passive component.

Please add the following new claims:

14. (New) The flip chip package of claim 1, wherein the resin was injected into a mold surrounding the chip and the substrate.
15. (New) A microelectronic device comprising:
 - a substrate comprising a first surface;
 - a chip comprising a first surface, a second surface, and one or more edges, the first surface of the chip being coupled with the first surface of the substrate by a plurality of solder bumps, the solder bumps providing electrical connection between the chip and the substrate; and
 - a solid resin element, the solid resin element resulting from a process of injecting liquid resin into a mold containing the chip and the substrate, the solid resin element encapsulating and bonding to the first surface of the chip, the one or more edges of the chip, the first surface of the substrate, and the plurality of solder bumps.
16. (New) The microelectronic device of claim 15, wherein the solid resin element is not bonded with the second surface of the chip.
17. (New) The microelectronic device of claim 16, wherein the second surface of the chip was in contact with the mold during the process of injecting liquid resin into the mold.
18. (New) The microelectronic device of claim 15, wherein the resin further comprises a filler material.

19. (New) The microelectronic device of claim 18, wherein the filler material comprises microspheres or microballoons.
20. (New) The microelectronic device of claim 19, wherein the microspheres or microballoons are comprised of silica.
21. (New) The microelectronic device of claim 19, wherein the microspheres or microballoons are comprised of glass.
22. (New) The microelectronic device of claim 15, wherein the resin comprises an epoxy.